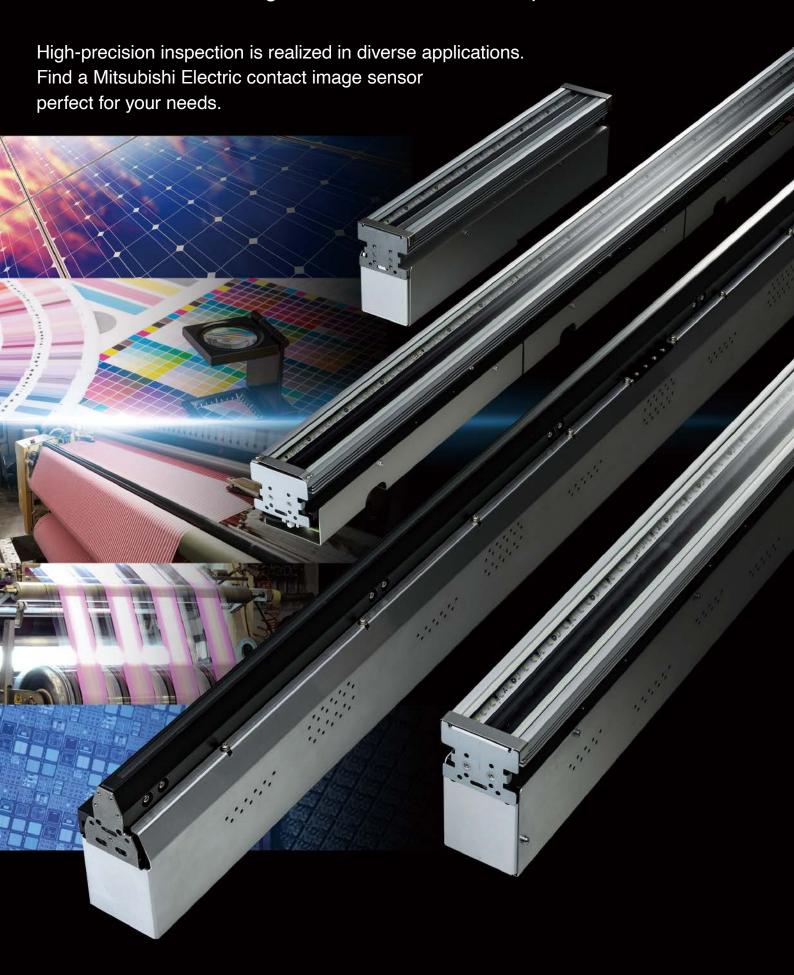


### KD Series Contact Image Sensors for Surface Inspection

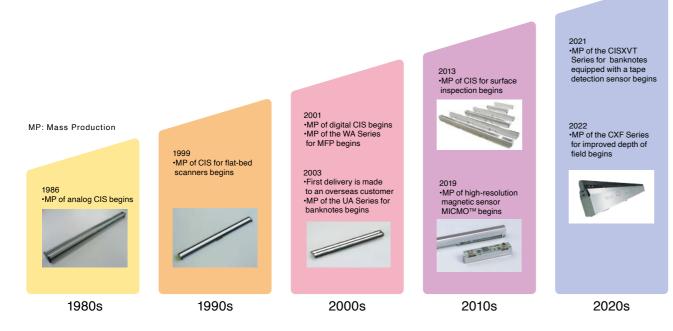


#### Mitsubishi Electric, as a leading company with years of experience in the CIS field,

### These contact image sensors embody the technologies and trust that Mitsubishi Electric has cultivated over more than 30 years

Mitsubishi Electric's CIS (Contact Image Sensor) business was launched in 1986. Since then, our contact image sensors have been delivered to diverse applications worldwide as high-quality image scanning devices. Based on the company's outstanding mounting technology and cutting-edge optical design technology, they combine an independently developed high-sensitivity CMOS image sensor and a signal processing feature catered to customer needs, and are used by customers throughout the world such as to achieve high-resolution, high-speed scanning by multifunction office machines and accurate reading of paper currency by banking terminals.

The KD Series Contact Image Sensors for Surface Inspection are imaging devices that utilize Mitsubishi Electric's long-standing CIS technology to realize high-performance surface inspection in a smarter and more simple manner. It can be applied to the surface inspection of printing, film, substrates, and other such objects along the production line, and can be used to detect and trace defects and flaws in manufacturing processes, thereby contributing to enhancing productivity and managing manufacturing quality and safety. As a leading company in the field, Mitsubishi Electric will continue to develop CIS technologies in response to diverse needs and propose new values.



#### Some examples of application to surface inspection

The KD Series Contact Image Sensor for Surface Inspection are suited for use in diverse applications, from the inspection to dimensional measurement of printing, labels, and packages, to detect scratches, stains, damage, coloring, position, etc.



Inline printing inspection (image)



PCB inspection (image)



Metal foil inspection (image)



Web inspection (image)



Wafer inspection (image)



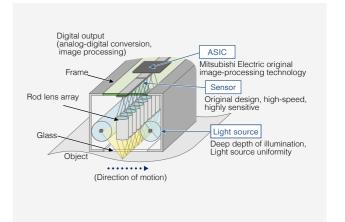
Battery electrode foil inspection (image)

#### has and will continue to provide high-quality products that satisfy customer needs.

### KD Series Contact Image Sensors realize high-precision inspection with a compact, easy-to-install design

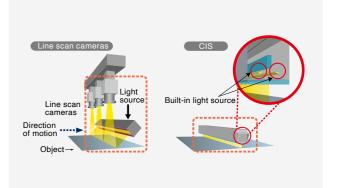
### An all-in-one module ensures easy and smooth installation

The sensor (Imaging element), light source (LED), and rod lens array (erect 1:1 image) are all built into the same frame. Therefore, the lens and light source do not need to be designed and procured separately, and installation is easy.



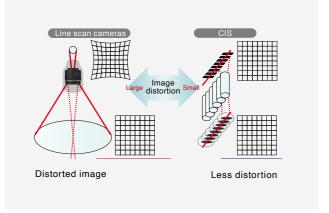
# A compact system that can scan large widths in one pass in response to diverse application needs

By selecting scanning widths that suit each application needs, entire scanning areas can be scanned in one pass without having to make adjustments. Furthermore, the sensor scans objects at close range, so it does not require a large space as does a line camera.



### Low-distortion scanning delivers greater accuracy in detecting flaws

The rod lens array (erect 1:1 image) is the same length as the scanning line. Therefore, even images from the edges of the sensor can be acquired without distortion on the edges, for accurate detection of flaws.



## Available with and without a built-in light source to match various needs

Models with a built-in light source incorporate a white LED array. Models without a built-in light source are suited for inspections that require various angles of light and special light sources.



#### AX/MX/CX/CXS Series A diverse lineup responds to diverse needs







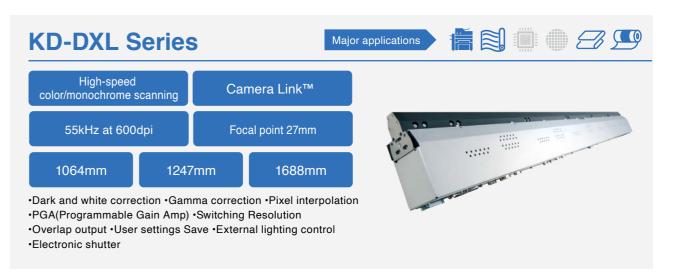
### SX Series Smallest KD-CIS model that takes up minimum space



#### CXL/CXF/DXL Series Scans widths up to 1688mm in one pass









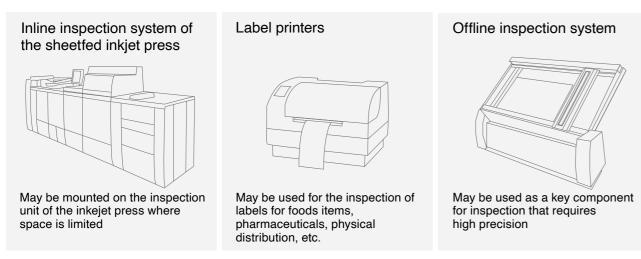
For information on other specifications and features, please refer the last page of this catalog or the documents for each model.

#### **Application examples**

#### Printing inspections

Mitsubishi Electric CIS for diverse printing inspection needs

High printing quality inspection can be achieved in diverse applications, from inline to offline inspection

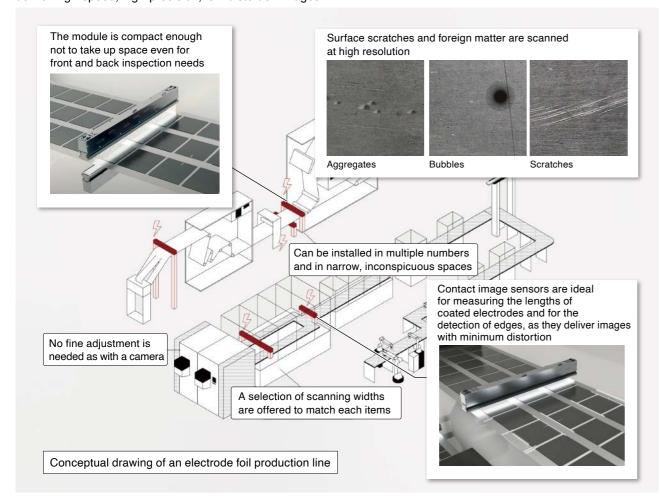


Recommended models: KD-AX, KD-CX, KD-CXL, KD-CXF, KD-SX

#### Lithium ion battery plant

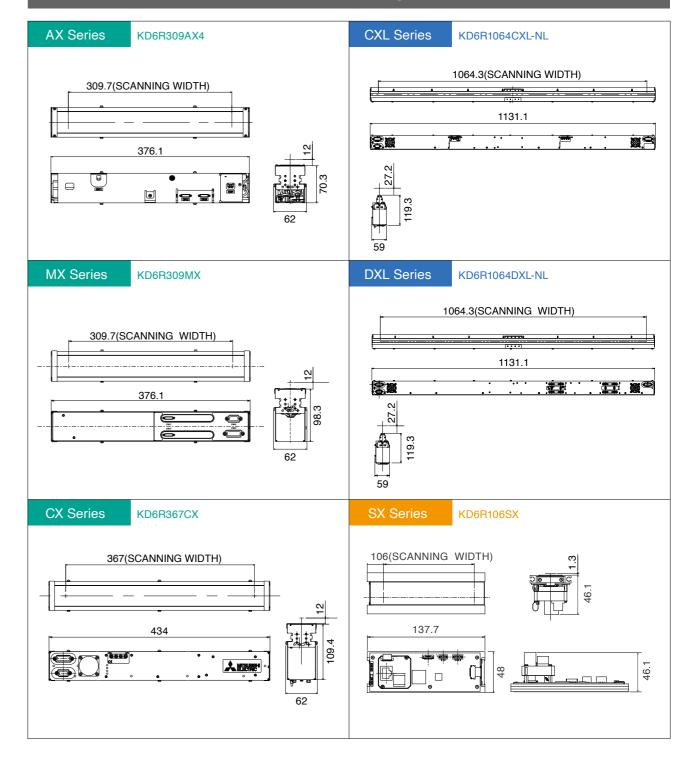
Mitsubishi Electric CIS for high-precision inspection in a variety of processes

Contact image sensors are ideal for the external inspection of secondary battery electrode foils and separators, as they deliver high-speed, high-precision, low-distortion images



Recommended models: KD-MX, KD-DXL

#### **Outline drawings**



#### What to prepare when using a contact image sensor

- •DC5V power supply •DC5V power supply cable •DC24V power supply
- •DC24V power supply cable •Interface cable (Camera Link™ cable, etc.)
- •PC equipped with a frame grabber board •Camera file

For details, please refer the user's manuals for each model.

A demo unit of each series is available, for use to scan images in your evaluation environment, to jointly evaluate work samples in our demonstration environment, or to evaluate images of work samples you place in our care.



### **Specifications**

			AX Series					MX Series		CX/CXS Series			
Imaging element			CMOS line sensor										
Optical system			Rod lens array										
Light source			LED array (both sides, white LED)										
Data output format				Camera	a Link™			Camera Link™		CoaXpress™ Rev1.1			
Resolution (dpi)				600/300	/200/150		600/300/150			600/300/200/150			
Scan width (mm)		309	619	929	335	309	619	929	367	587	807		
Valid pixe	Valid pixels (pixel)		7,319	14,639	21,959	7,929	7,319	14,639	21,959	8,669	13,871	19,073	
	600dpi		22			20	44			55			
Line rate (kHz)	300dpi		31			27				96			
	200dpi						-			130			
	150dpi						44			159			
Scan speed (m/s) Max speed	600dpi		0.9			0.9	1.9			2.3			
	300dpi		2.6			2.3	3.7			8.1			
	200dpi		3.9			3.4		-		16.5			
	150dpi		5.3			4.6		7.5		26.9			
Focal point	Built-in light source		12				12			12			
(mm)	No light source		14.5			-		14.5		14.5			
CE certification			)	-	0		0		0				
Ro	RoHs			RoHS2 compliance									
Environmental temperature(°C)			5 - 50										
Ext. dimensions (mm)	Built-in light	L	376.1	687.1	996.1	376.1	376.1	687.1	996.1	434	654	874	
		D	62			62			62				
	source	Н	70.3					98.3		109.4			
	No light source	L	376.1	687.1	996.1	-	376.1	687.1	996.1	434	654	874	
		D	62		-	62			62				
		Н		67.1		-		94.8			105.9		
Weight (kg)	Built-in light source		1.7	3.1	4.5	1.7	1.9	3.3	4.8	2.6	3.9	5.1	
	No light source		1.2	2.3	3.3	-	1.2	2.3	3.3	1.9	2.9	3.8	

				CXL Series			DXL Series		SX Series			
Imaging element			CMOS line sensor									
Optical system			Rod lens array									
Light source					LED (both sides, red LED)							
Data output format			Co	aXpress™ Rev	1.1		Camera Link™		GigE Vision™ Rev2.0			
Resolution (dpi)			(	600/300/200/150	)		600/300/200/15	0	600			
Scan wi	Scan width (mm)			1247	1688	1064	1247	1688	106			
Valid pix	Valid pixels (pixel)		25,142	29,477	39,881	25,142	29,477	39,881	2,504			
	600dpi		55	4	7	35 29		9	6			
Line rate	300dpi		96	96 94			60					
(kHz)	200dpi		130			104	88		-			
	150dpi		159			134	114					
0	600dpi		2.3	2.3 2.0			1.2		0.3			
Scan speed (m/s) Max speed	300dpi		8.1	8	.0	6.1	5.1					
	200dpi		16.5	16.5	16.5	13.2	11.2		-			
Wax speed	150dpi		29.9	29.9	29.9	22.7	19.3					
Focal point	Built-in light source			-		-			1.3			
(mm)	No light source			27		27			=			
CE certification		0 -			0 -			-				
Ro	RoHs			RoHS2 compliance								
Environmental t	Environmental temperature(°C)			5 - 50								
	Built-in light source	L				-			137.7			
Ext. dimensions (mm)		D		-					48			
		Н							46.1			
	No light source	L	1131.1	1314.1	1755.1	1131.1	1314.1	1755.1				
		D	59 119.3			59			-			
		Н				119.3						
Weight (kg)	Built-in light source		-			-			1.7			
	No light source		5.3	6.2	8.4	5.8	6.7	9.1	=			

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Integrated Sensing Systems Division Electric Devices Marketing and Business Development Department

Electric Devices and Meteorological Systems Section